

Search Notes



Application/Control No.

10/693,896

Examiner

Stephen W. Smoot

Applicant(s)/Patent under Reexamination

CHEN ET AL.

Art Unit

2813

SEARCHED

Class	Subclass	Date	Examiner
438	108	1/27/2005	SWS
438	612	1/27/2005	SWS
438	613	1/27/2005	SWS
438	614	1/27/2005	SWS
257	738	1/27/2005	SWS
257	E21.508	1/27/2005	SWS
29	842	1/27/2005	SWS
Updated	Above	5/9/2005	SWS
438	615	5/9/2005	SWS
228	180.22	5/9/2005	SWS

INTERFERENCE SEARCHED

Class	Subclass	Date	Examiner
Same as Above		5/9/2005	SWS

SEARCH NOTES (INCLUDING SEARCH STRATEGY)

	DATE	EXMR
Key Words: Solder Ball, Bump - Flux; Active Surface; Bond Pad; Under Bump Metallurgy;	1/27/2005	SWS
Passivation Layer; Solder Reflow; Solid Flux.	1/27/2005	SWS
Updated Above Search	5/9/2005	SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	1/27/2005 5-9-05	SWS